## **Supplemental Materials:**

## Reaction at buried Ti/ZnO thin film interface as seen by hard x-ray

## photoemission and thermal desorption spectroscopy

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## 1. Complementary Figures



Fig. S1. (a) HAXPES spectrum of a  $Si_{wafer}/ZnO(29.7nm)/Mo(4.9nm)$  sample in the Ti 2p core level region showing the linear behavior of the Mo 3p inelastic background. (b) Example of the linear background subtraction methodology on the  $Si_{wafer}/ZnO(29.7nm)/Ti(3.6nm)/Mo(4.9nm)$  sample.



Fig. S2. Fit of Ti 2*p* core level of (a) Si<sub>wafer</sub>/Ti(44.1nm)/Mo(4.9nm) and (b) Si<sub>wafer</sub>/TiO<sub>2</sub>(20nm)/Mo(5.0nm) reference stacks with mainly (a) metallic Ti<sup>0</sup> and (b) fully oxidized Ti<sup>4+</sup> components: (red circles): data, (black line): fit, (dotted line): background; (blue line): residue, (others) indicated oxidation states of Ti.



Fig. S3. Fit of Zn 2*p* core level of (a) Si<sub>wafer</sub>/Zn(15nm) and (b) Si<sub>wafer</sub>/ZnO(29.9nm)@RT reference stacks. The unfortunate lack of capping leads to a surface contamination peak (oxidized Zn and/or hydroxydes): (red circles): data, (black line): fit, (dotted line): background; (blue line): residue, (others) bulk and surface peaks.



Fig. S4. Evolution of Zn 2*p 3/2* core level of the <u>29.7@RT</u> stack (Si<sub>wafer</sub>/Zn0(29.7nm)/Ti(3.5nm)/Mo(5nm)): upon annealing on (a) an absolute scale of intensity and (b) after normalization to the peak

maximum. The inset shows the profiles of Zn 2p 3/2 for the above discussed metallic Zn and ZnO references.



Fig. S5. <sup>64</sup>Zn TDS signals for (a) Si<sub>wafer</sub>/Zn(1.3nm)/Mo(3.0nm) (b) Si<sub>wafer</sub>/Zn(1.6nm)/Ti(3.3nm)/Mo(3.0nm) and (c) Si<sub>wafer</sub>/ZnO(1.8nm)/TiO<sub>x</sub>(4.0nm)/Mo(3.0nm) samples as a function of temperature.



Fig. S6. (a) Ti - Zn phase diagram simulated by *FactSage* software at atmospheric pressure. (b) diagram proposed by Vassilev *et al.* [44].



Fig. S7. (a) ZnO-TiO<sub>2</sub> phase diagram simulated by *FactSage* software at atmospheric pressure. (b) diagram proposed by Yang *et al.* [45]. The vertical dotted line corresponds to the molar fraction of 33% of Ti corresponding to film thicknesses ZnO(9.5 nm)/Ti(3.4 nm).



Fig. S8. Mo – Ti phase diagram simulated by *FactSage* software at 10<sup>-7</sup>Pa.



Fig. S9. Zn – Mo phase diagram simulated by *FactSage* software at 10<sup>-7</sup>Pa.



Fig. S10. Ti – Zn phase diagram simulated by *FactSage* software at 10<sup>-7</sup>Pa.